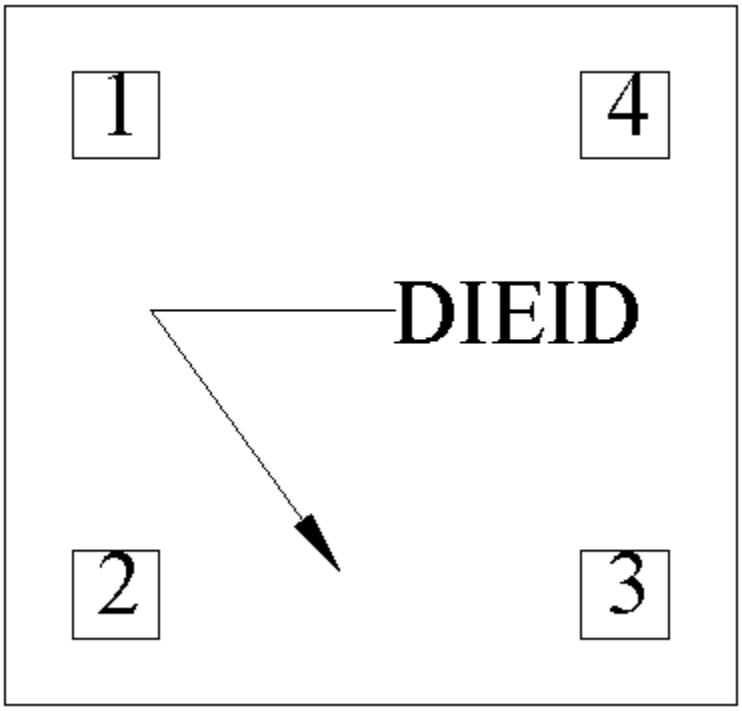
LM20BI MDC MCD1640A
2.4V, 10µA, TEMPERATURE SENSOR

June 18,2003

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		**General Die Information**	
Physical Die Identification	LM20A	Bond Pad Opening Size (min)	69µm x 69µm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	NITRIDE
Wafer Diameter	200mm	Back Side Metal	BARE BACK
Die Size (Drawn)	584µm x 559µm 23.0mils x 22.0mils	Back Side Connection	Floating or GND
Thickness	216µm Nominal		
Min Pitch	382µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
VO	1	-203	191	69	x	69
NC	2	-203	-191	69	x	69
GND	3	203	-191	69	x	69
V+	4	203	191	69	x	69

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